Title (en)

CYANIDE-FREE SUBSTITUTION GOLD PLATING SOLUTION COMPOSITION

Title (de)

GOLDPLATTIERUNGSLÖSUNGSZUSAMMENSETZUNG DURCH CYANIDFREIE SUBSTITUTION

Title (fr)

COMPOSITION DE TYPE SOLUTION DE PLACAGE D'OR DE SUBSTITUTION SANS CYANURE

Publication

EP 3564407 A1 20191106 (EN)

Application

EP 16925513 A 20161227

Priority

JP 2016089007 W 20161227

Abstract (en)

A gold deposition accelerator for electroless gold plating comprising one or more alkali metal compound(s), wherein said alkali metal compound is not a compound comprising only sodium as an alkali metal, and said alkali metal compound is not only halide, only potassium sulfite, or only potassium sodium tartrate of an alkali metal, an electroless gold plating solution comprising said gold deposition accelerator, a gold plating method and a gold deposition accelerating method using the same and the like are provided.

IPC 8 full level

C23C 18/44 (2006.01)

CPC (source: EP KR US)

C23C 18/42 (2013.01 - EP KR US); **C23C 18/44** (2013.01 - EP KR)

Designated contracting state (EPC)

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Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

EP 3564407 A1 20191106; **EP 3564407 A4 20201021**; CN 110114507 A 20190809; JP 6842475 B2 20210317; JP WO2018122989 A1 20191226; KR 20190096420 A 20190819; US 2021095378 A1 20210401; WO 2018122989 A1 20180705

DOCDB simple family (application)

EP 16925513 A 20161227; CN 201680091924 A 20161227; JP 2016089007 W 20161227; JP 2018558587 A 20161227; KR 20197021607 A 20161227; US 201616473764 A 20161227